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**UPDATE NOTIFICATION  
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**06-DEC-2001**

**SUBJECT: ON Semiconductor Update Notification 12094**

**TITLE: Addendum To FPCN# 11734: Final Notification - Qualification of Assembly and Test Site for TO220FP (Case 221D-02) Products**

**EFFECTIVE DATE: 06-Dec-2001**

**AFFECTED CHANGE CATEGORY:**  
ON Semiconductor Assembly Site  
Subcontractor Assembly Site

**AFFECTED PRODUCT DIVISION: Bipolar Discretes Products Division**

**ADDITIONAL RELIABILITY DATA: Available**  
Contact your local ON Semiconductor Sales Office  
or Terry Franks <t.franks@onsemi.com>

**SAMPLES:** Contact your local ON Semiconductor Sales Office  
or Jose Ramirez <rveg40@onsemi.com>

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**  
Contact Sales Office or Jose Ramirez <rveg40@onsemi.com>

**DISCLAIMER:**  
Initial Product/Process Change Notification (IPCN) - First Notification distributed to customers. Distributed at least 120 days from the effective date of the change.

Final Product/Process Change Notification (FPCN) - Final Notification completing the notification process. Distributed at least 60 days from the effective date of the change. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

**DESCRIPTION AND PURPOSE:**  
This is in reference to FPCN#11734 in which ON Semiconductor will be qualifying PSI Technologies at Manila, Philippines to Assembly and Test all TO220FP (Case 221D-02) Products. In this addendum, the package dimensions of ON Semiconductor and PSI Technologies Products are listed here below.



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Dim	ON Semiconductor		PSi Technologies	
	Min	Max	Min	Max
A	0.621	0.629	0.6245	0.6345
B	0.394	0.402	0.4084	0.4184
C	0.181	0.189	0.180	0.190
D	0.026	0.034	0.0256	0.0306
F	0.121	0.129	0.116	0.119
G		0.100BSC		0.100 BSC
H	0.123	0.129	0.125	0.135
J	0.018	0.025	0.0177	0.0247
K	0.500	0.562	0.5304	0.5404
L	0.045	0.060	0.0484	0.0534
N		0.200 BSC		0.200 BSC
Q	0.126	0.134	0.124	0.128
R	0.107	0.111	0.099	0.103
S	0.096	0.104	0.1013	0.113
U	0.259	0.267	0.2384	0.2584

**DESCRIPTION:**

Dimension A = Plastic package body height  
 Dimension B = Plastic package body width  
 Dimension C = Plastic package body thickness  
 Dimension D = Leads width  
 Dimension F = Mounting hole diameter  
 Dimension G = Center of lead to center of lead distance  
 Dimension H = Upper body lead length  
 Dimension J = Leads thickness  
 Dimension K = Total lead length  
 Dimension L = Upper body lead width  
 Dimension N = Distance center to center outside leads  
 Dimension Q = Distance center mounting hole to top tab  
 Dimension R = Distance lead to package back surface (Seating Plane)  
 Dimension S = Plastic isolated mounting tab body width  
 Dimension U = Plastic isolated mounting tab body length

**RELATED NOTIFICATIONS:**

- 11678 - INITIAL NOTIFICATION - QUALIFICATION OF ALTERNATE ASSEMBLY/TEST SITES FOR POWER PRODUCTS
- 11734 - FINAL NOTIFICATION - QUALIFICATION OF ASSEMBLY AND TEST SITE FOR TO220FP (CASE 221D-02)PRODUCTS.

**AFFECTED DEVICE LIST (WITHOUT SPECIALS)**

**PART**

BUL146F, MBRF20100CT, MBRF20200CT,  
 MBRF2060CT, MBRF2545CT, MJF122,  
 MJF127, MJF15030, MJF15031,  
 MJF18004, MJF18008, MJF2955,  
 MJF3055, MJF31C, MJF32C,  
 MJF44H11, MJF45H11, MJF47,  
 MJF6388, MJF6668, MURF1620CT,  
 MURF1660CT, MURHF860CT,